

PACKAGING & ASSEMBLY

Wafer Prober

Manufacturer: Süss Microsystems /
Cascade microtech

Model: PM8 manual probing system



General Description:

A wafer prober can be equipped with several probing tips to establish electrical contact(s) to bare chips by contacting the bonding pads. The applied tips allow to connect different measurement devices e.g. digital multimeters, source meters, rf-generators or network analyzers. Pad size, pad distance(s) and pad position on the chip are the boundary conditions according to which the probing tip(s) are to be chosen.

Key Specifications:

- Manual xyz – manipulation stages with precision tip holders
- Vacuum system to fix device under test on probing table (chuck)
- Heated ceramic plate and special tips allow for device tests up to 600°C
- RF and DC measurements possible
- Probing tips in any format, DC and RF possible, e.g. GSG with 150µm pitch, GS with 500µm pitch up to 1250µm or single tungsten needles for DC contacting
- Max. Wafer size: 6 inches

Availability	Use allowed for all researchers with permission
Location	Cleanroom C8 Europastraße 12 9524 Villach
Responsibles / Contact	Dr. Jochen Bardong / Dr. Gudrun Bruckner Tel.:+43 4242 56300 209/235